

IN THE SPECIFICATION

Please amend the specification as follows:

Replace the paragraph spanning pages 9-10, between page 9, line 24, and page 10, line 2 of the specification with the following:

~~FIG. 2 shows~~ FIGs. 2a-2d show an alternative way of forming a barrier layer 22 on the first surface 12. The same stamp 10 as shown in FIG. 1a is again depicted in FIG. 2a. As shown in FIG. 2b, the stamp 10 is modified by dipping the first surface 12 in a layer of an uncured polymer 220, which has been deposited on a carrier 200. Such a polymer may be formed from epoxides, acrylates or other suitable compounds. This deposition may for instance be realized by means of a spin coating technique, with the thickness of the layer being controlled by the parameters of the spin coating process, e.g., polymer concentration, and spinning conditions such as rotation speed, temperature and so on. The layer of the uncured polymer typically has a submicron thickness, e.g., 50-100 nm.

Replace the paragraph on page 10, between lines 27-32 of the specification with the following:

An alternative way of forming a polymer barrier layer on a surface of stamp 10 is shown in ~~FIG. 3~~ FIGs. 3a-3e. A master 300 for forming an elastomeric stamp has a first surface 312 in a first plane, a second surface 314 in a second plane and a third surface 316 extending from the first surface 312 to the second surface 314, as shown in FIG. 3a. The master 300 may be formed from a suitable material such as silicon.

Replace the paragraph on page 12, between lines 1-7 of the specification with the following:

Another way of providing a stamp 10 with a barrier layer 22 is shown in ~~FIG. 4~~ FIGs. 4a-4c. The first surface 12 of the stamp 10 shown in FIG. 3a may be subjected to an oxidizing agent 400 such as a peroxide, as shown in FIG. 4b. Consequently, the first material of the stamp 10 is oxidized at the contact surfaces with the oxidizing agent 400, thus forming a stamp 10 having a barrier layer

22 on the first surface 12, with the barrier layer 22 comprising the first material in an oxidized form, as shown in FIG. 3c.